

Maximum Ratings @TA = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Peak Pulse Power (tp = 8x20µs, per Figure 2)	P _{PK}	300	W
Peak Forward Voltage (IPP = 1A, tp = 8x20µs, per Figure 2)	V_{FP}	2.1	V
Diode Peak Repetitive Reverse Voltage	V_{RRM}	75	V

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance, Junction to Ambient (Note 10)	$R_{\Theta JA}$	417	°C/W
Operating and Storage Temperature Range	T_J,T_STG	-55 to +150	°C

Electrical Characteristics @TA = 25°C unless otherwise specified

Reverse Standoff Voltage		n Voltage @ I _T	Test Current	Max. Reverse Leakage @ V _{RWM} (Note 9)	Max. Clamping Voltage @ I _{pp} = 1A (Note 8)	Typical Peak Pulse Current (Note 7)	Typical Total Capacitance (Note 6)
V _{RWM} (V)	Min (V)	Max (V)	I _T (mA)	I _R (μ A)	V _C (V)	(A)	(pF)
5	6.0		1.0	20	9.8	17	1.9

Notes:

- 6. $V_R = 0V$, f = 1MHz from line to be protected to ground pin.
- 7. $tp = 8 \times 20 \mu s$.
- 8. Clamping voltage value is based on an $8\times20\mu s$ peak pulse current (I_{pp}) waveform.
- 9. Short duration pulse test used to minimize self-heating effect.
- 10. Device mounted on FR-4 PCB pad layout (2oz copper) as shown on Diodes, Inc. suggested pad layout AP02001, which can be found on our website at http://www.diodes.com.



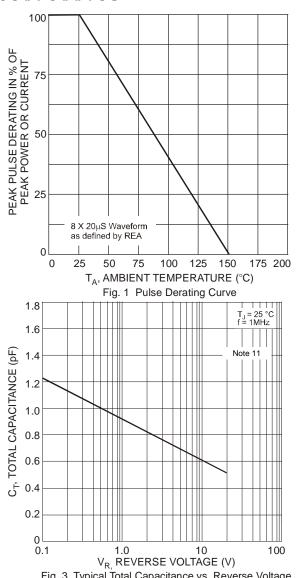


Fig. 3 Typical Total Capacitance vs. Reverse Voltage

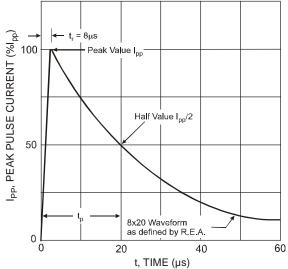
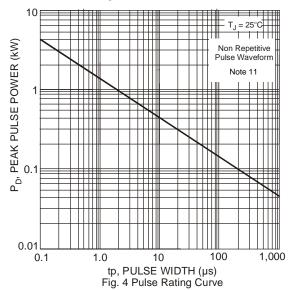


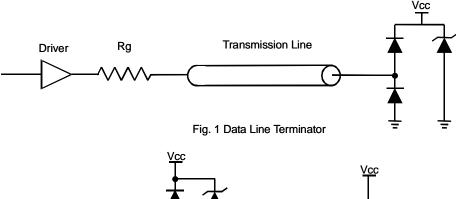
Figure 2. Pulse Waveform



Notes: 11. Measured from line to be protected to ground pin.



Typical Application Schematics



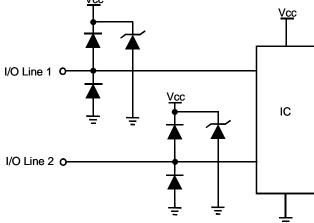
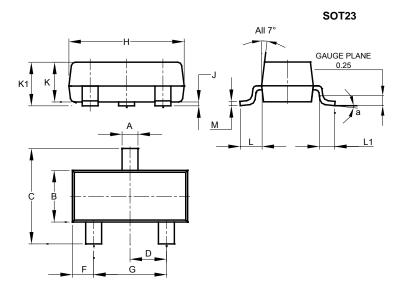


Fig. 2 Data Line Protection



Package Outline Dimensions

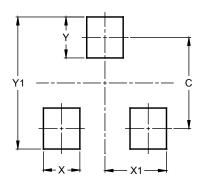
Please see http://www.diodes.com/package-outlines.html for the latest version.



SOT23				
Dim	Min	Max	Тур	
Α	0.37	0.51	0.40	
В	1.20	1.40	1.30	
С	2.30	2.50	2.40	
D	0.89	1.03	0.915	
F	0.45	0.60	0.535	
G	1.78	2.05	1.83	
Н	2.80	3.00	2.90	
J	0.013	0.10	0.05	
K	0.890	1.00	0.975	
K1	0.903	1.10	1.025	
L	0.45	0.61	0.55	
L1	0.25	0.55	0.40	
М	0.085	0.150	0.110	
а	a 0° 8°			
All Dimensions in mm				

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



SOT23

Dimensions	Value (in mm)
С	2.0
Х	0.8
X1	1.35
Y	0.9
Y1	29



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